



DDR2 SO DIMM

TE Internal #: 1612773-4  
Double Data Rate (DDR) 2, 6.5 mm [.256 in] Stack Height, Right Angle Module Orientation, 200 Position, DDR2 SO DIMM, SO DIMM Sockets

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Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets > DDR2 SO DIMM Sockets



DRAM Type: Double Data Rate (DDR) 2  
Stack Height: 6.5 mm [.256 in]  
Module Orientation: Right Angle  
Number of Positions: 200  
Centerline (Pitch): .6 mm [.024 in]

[All DDR2 SO DIMM Sockets \(28\)](#)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Cable-to-Board
DRAM Type	Double Data Rate (DDR) 2

Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	200

Electrical Characteristics

DRAM Voltage	1.8 V
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Signal Characteristics

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SGRAM Voltage	1.8 V
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Body Features

Latch Material	Stainless Steel
Module Key Type	SGRAM
Ejector Type	Locking
Ejector Location	Both Ends
Connector Profile	Standard

Contact Features

Contact Current Rating (Max)	.5 A
Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Gold Flash
Contact Mating Area Plating Material	Gold Flash

Termination Features

Insertion Style	Cam-In
Termination Method to PCB	Surface Mount

Mechanical Attachment

Connector Mounting Type	Board Mount
PCB Mount Retention Type	Solder Peg
Mating Alignment Type	Reverse Keying
PCB Mount Retention	With

Housing Features

Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.6 mm[.024 in]

Dimensions

Stack Height	6.5 mm[.256 in]
Row-to-Row Spacing	6.2 mm[.244 in]

Usage Conditions

Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]
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Operation/Application

Circuit Application	Power
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Industry Standards

UL Flammability Rating	UL 94V-0
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Packaging Features

Packaging Quantity	20
Packaging Method	Semi-Hard Tray Assembly

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

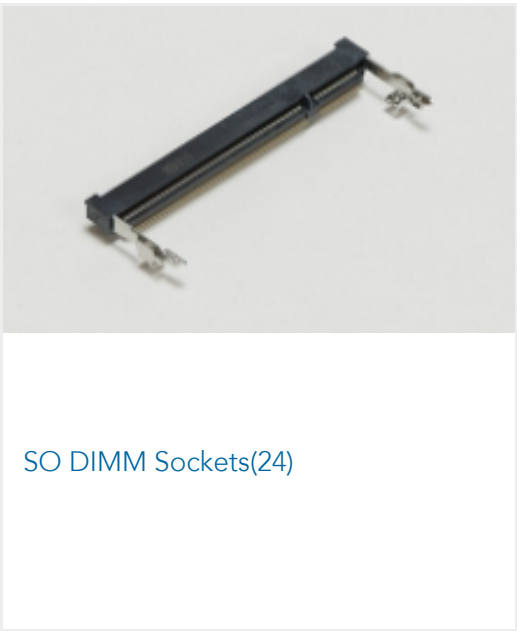
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) ‘Guidance on requirements for substances in articles’ posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts



Also in the Series | DDR2 SO DIMM



Customers Also Bought

TE Part #2301845-2  
AMPL REC HD20, R/A, 15P, B/L,4-40 A /LOCK

TE Part #1-1903131-2  
DYNAMIC 1200D TAB HSG 4P P/M

TE Part #2-292252-2  
CT DOUBLE ROW ASSY V 22P HDR N

TE Part #1376135-1  
DYNAMIC D2100 HDR H ASSY 3P X

TE Part #3-1461491-0  
PCN-105D3MHZ,000

TE Part #1-2176326-3  
CRGP 0603 100R 1%

TE Part #7-338069-6  
MICRO-MATCH SMD FTE

TE Part #1-178138-2  
DYNAMIC 3200 HDR H 3P ASSY

TE Part #5-2176337-7  
CRGCO 0402 470K 1%

TE Part #1-1879234-6  
SMF5 2K2 5%



Documents

Product Drawings

SEMI-HARD TRAY DDR2 SODIMM SOCKET 200P 6

English

CAD Files

Customer View Model

ENG\_CVM\_CVM\_1612773-4\_G1.2d\_dxf.zip

English

3D PDF

3D

Customer View Model

ENG\_CVM\_CVM\_1612773-4\_G1.3d\_igs.zip

English

Customer View Model

ENG\_CVM\_CVM\_1612773-4\_G1.3d\_stp.zip

English

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Product Specifications

Application Specification

English